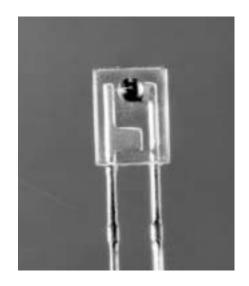
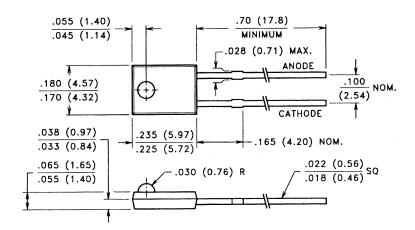
# **GaAlAs Infrared Emitting Diodes**

Molded Lateral Package — 880 nm

# VTE7172, 7173



#### PACKAGE DIMENSIONS inch (mm)



### **DESCRIPTION**

CASE 7 LATERAL CHIP SIZE: .011" x .011"

These side-looking packages are designed for use in PC board mounted interrupt detectors. The package is transfer molded plastic and contains a high efficiency, 880 nm, GaAlAs IRED die.

#### ABSOLUTE MAXIMUM RATINGS @ 25°C (unless otherwise noted) ■

Maximum Temperatures		Maximum Reverse Voltage:	5.0 <b>V</b>
Storage and Operating:	-40°C to 85°C	Maximum Reverse Current @ V <sub>R</sub> = 5V:	10 μA
Continuous Power Dissipation:	100 mW	Peak Wavelength (Typical):	880 nm
Derate above 30°C:	1.82 mW/°C	Junction Capacitance @ 0V, 1 MHz (Typ.):	14 pF
Maximum Continuous Current:	50 mA	Response Time @ $I_F = 20 \text{ mA}$	•
Derate above 30°C:	0.91 mA/°C	Rise: 1.0 µs Fall: 1.0 µs	
Peak Forward Current, 10 µs, 100 pps:	2.5 A	Lead Soldering Temperature:	260°C
Temp. Coefficient of Power Output (Typ.):	8%/°C	(1.6 mm from case, 5 seconds max.)	

## ELECTRO-OPTICAL CHARACTERISTICS @ 25°C (See also GaAlAs curves, pages 108-110)

	Output						Forward Drop		Half Dawar Daam	
Part Number	Irradiance			Radiant Intensity	Total Power	Test Current	V <sub>F</sub>		Half Power Beam Angle	
	E <sub>e</sub> Con		dition	I <sub>e</sub>	P <sub>O</sub>	I <sub>FT</sub>	@	I <sub>FT</sub>	θ <sub>1/2</sub>	
	mW/cm <sup>2</sup>		distance	Diameter	mW/sr	mW	mA	Volts		Tup
	Min.	Тур.	mm	mm	Min.	Тур.	(Pulsed)	Тур.	Max.	Тур.
VTE7172	0.4	0.6	16.7	4.6	1.1	2.5	20	1.3	1.8	±25°
VTE7173	0.6	0.8	16.7	4.6	1.7	5.0	20	1.3	1.8	±25°

■ Refer to General Product Notes, page 2.